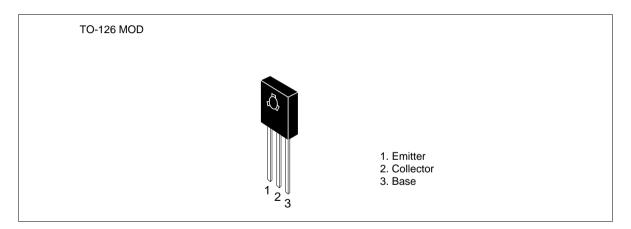
Silicon NPN Epitaxial

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Application

Power switching / TV horizontal deflection output

Outline



Absolute Maximum Ratings ($Ta = 25^{\circ}C$)

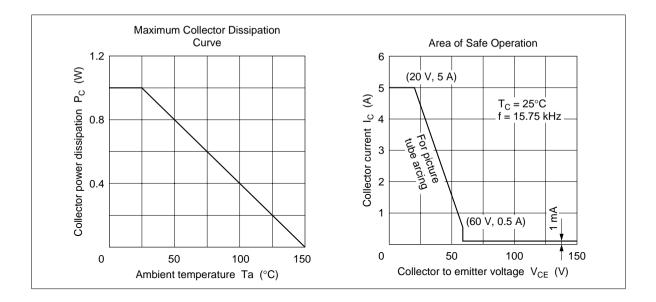
Item	Symbol	Ratings	Unit
Collector to base voltage	V _{CBO}	150	V
Collector to emitter voltage	V _{CEO}	60	V
Emitter to base voltage	V _{EBO}	5	V
Collector current	Ι _c	2	А
Collector peak current	I _{C(peak)}	2.5	А
Collector surge current	I _{C(surge)}	5	А
Collector power dissipation	Pc	1.0	W
Junction temperature	Tj	150	°C
Storage temperature	Tstg	-55 to +150	°C

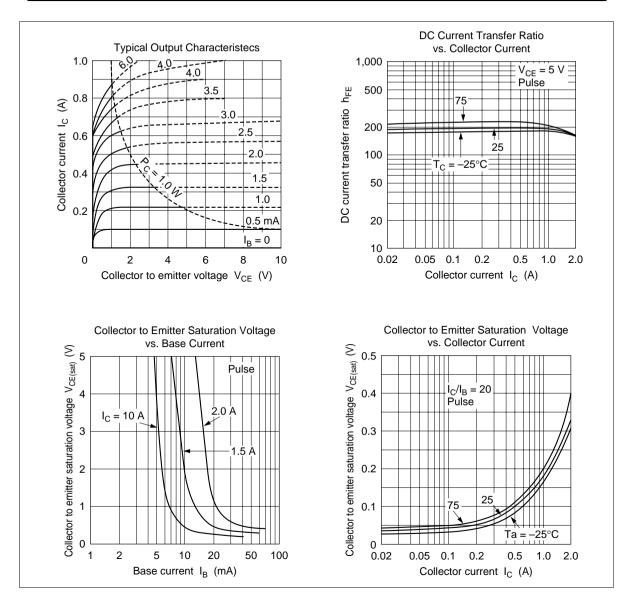


Electrical Characteristics (Ta = 25°C)

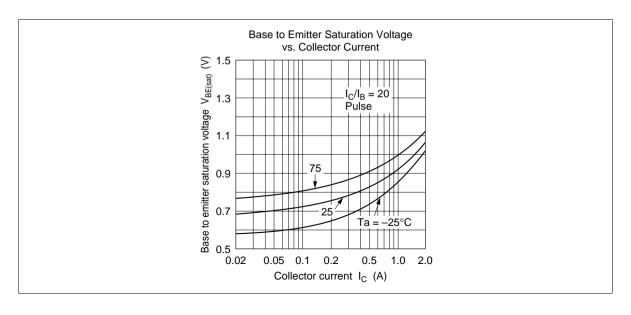
Item	Symbol	Min	Тур	Мах	Unit	Test conditions
Collector to base breakdown voltage	$V_{\rm (BR)CBO}$	150	_	_	V	$I_{c} = 1 \text{ mA}, I_{E} = 0$
Collector to emitter breakdown voltage	$V_{\rm (BR)CEO}$	60	_	_	V	$I_c = 10$ mA, $R_{_{BE}} = \infty$
Emitter to base breakdown voltage	$V_{(\text{BR})\text{EBO}}$	5	_	_	V	$I_{\rm E} = 1$ mA, $I_{\rm C} = 0$
Collector cutoff current	I _{CBO}	_	_	1.0	μΑ	$V_{CB} = 100 \text{ V}, I_{E} = 0$
DC current transfer ratio	h _{FE}	150	_			$V_{ce} = 5 \text{ V}, \text{ I}_{c} = 1.5 \text{ A}^{*1}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	_	_	0.5	V	$I_{\rm C} = 1.5 \text{ A}, I_{\rm B} = 0.05 \text{ A}^{*1}$
Base to emitter saturation voltage	$V_{\text{BE(sat)}}$	_	_	1.3	V	_
Fall time	t _f	—	_	0.6	μs	$I_{c} = 1.5 \text{ A}, I_{B1} = -I_{B2} = 50 \text{ mA}$

Note: 1. Pulse test.



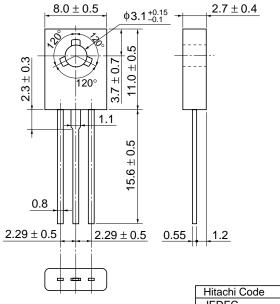


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Unit: mm



Hitachi Code	TO-126 Mod
JEDEC	
EIAJ	_
Weight (reference value)	0.67 g

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